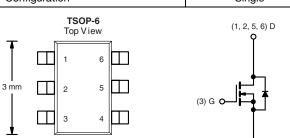


www.vishay.com

Vishay Siliconix

# Automotive N-Channel 20 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	20			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.055			
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 2.5 \text{ V}$	0.085			
I <sub>D</sub> (A)	4.3			
Configuration	Single			



\_ 2.85 mm ·

Marking Code: 8Fxxx

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- AEC-Q101 Qualified<sup>c</sup>
- 100 % Rq and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and Halogen-free	SQ3442EV-T1-GE3

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	<b>S</b> (1 <sub>C</sub> = 25 °C, unles	s otherwise noted	d)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		$V_{DS}$	20	V
Gate-Source Voltage		$V_{GS}$	± 8	
Continuous Drain Current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	4.3	
	T <sub>C</sub> = 125 °C		2.5	
Continuous Source Current (Diode Conduction)		Is	2.2	А
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	17	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	6	
Single Pulse Avalanche Energy	L = 0.1 MH	E <sub>AS</sub>	1.8	mJ
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	1.7	w
	T <sub>C</sub> = 125 °C		0.6	
Operating Junction and Storage Temperature	e Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient P	CB Mount <sup>b</sup>	R <sub>thJA</sub>	120	°C/W
Junction-to-Foot (Drain)		R <sub>thJF</sub>	85	C/VV

### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. Parametric verification ongoing.



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	1			I.	ı	ı		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		20	-	-	V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		1	1.6		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$		-	-	± 100	nA	
Zero Gate Voltage Drain Current		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 20 V	=.	-	1		
	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 20 V, T <sub>J</sub> = 125 °C	=.	-	50	μΑ	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 20 V, T <sub>J</sub> = 175 °C	-	-	150		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 4.5 V	$V_{DS} \ge 5 V$	10	-	-	Α	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 4 A	-	0.044	0.055	Ω	
Dunin Course On Chata Basistanas		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 4 A, T <sub>J</sub> = 125 °C	-	-	0.080		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 4 A, T <sub>J</sub> = 175 °C	-	-	0.094		
		V <sub>GS</sub> = 2.5 V	I <sub>D</sub> = 3.4 A	-	0.060	0.085		
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4 A		-	14	-	S	
Dynamic <sup>b</sup>								
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	= 0 V V <sub>DS</sub> = 10 V, f = 1 MHz	-	323	405	pF	
Output Capacitance	C <sub>oss</sub>			=.	71	90		
Reverse Transfer Capacitance	C <sub>rss</sub>	]		=.	45	60		
Total Gate Charge <sup>c</sup>	Qg	V <sub>GS</sub> = 4.5 V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A	-	3.5	5.5	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			-	0.6	-		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	0.8	-		
Gate Resistance	$R_g$	f = 1 MHz		0.9	1.85	2.8	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	5	8		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 10 \text{ V, } R_L = 10 \Omega$ $I_D \cong 1 \text{ A, } V_{GEN} = 4.5 \text{ V, } R_g = 1 \Omega$		-	15	23	- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	14	21		
Fall Time <sup>c</sup>	t <sub>f</sub>			-	6	9		
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>							
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	17	Α	
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 1.6 A, V <sub>GS</sub> = 0		-	0.75	1.2	V	

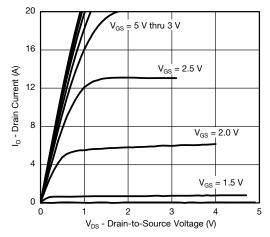
### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

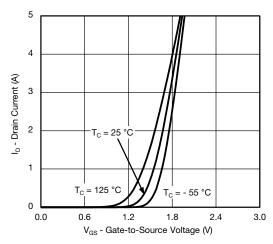
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



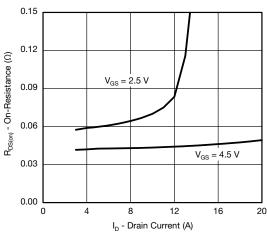
## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



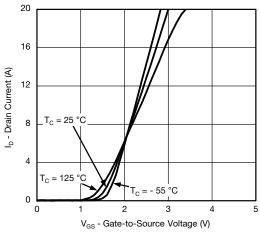
### **Output Characteristics**



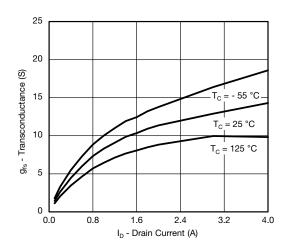
#### **Transfer Characteristics**



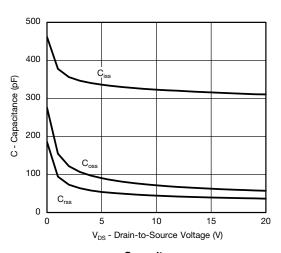
On-Resistance vs. Drain Current



**Transfer Characteristics** 



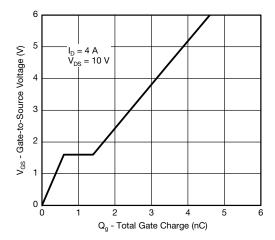
Transconductance



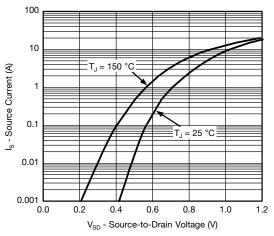
Capacitance



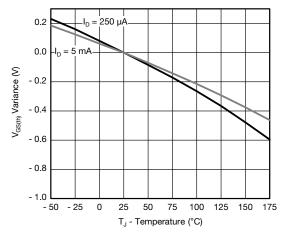
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



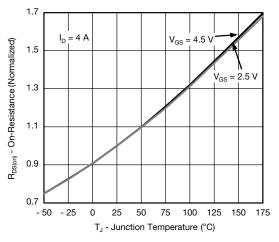
#### **Gate Charge**



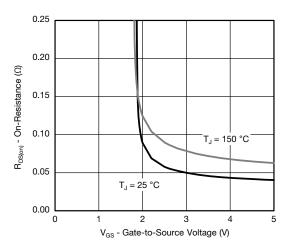
Source Drain Diode Forward Voltage



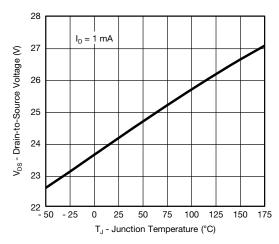
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



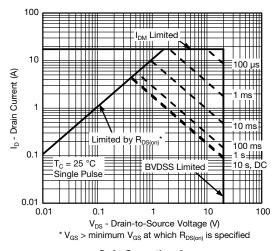
On-Resistance vs. Gate-to-Source Voltage



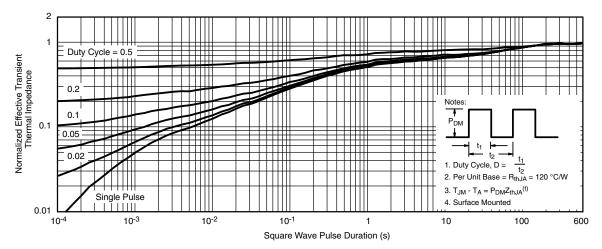
**Drain Source Breakdown vs. Junction Temperature** 



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



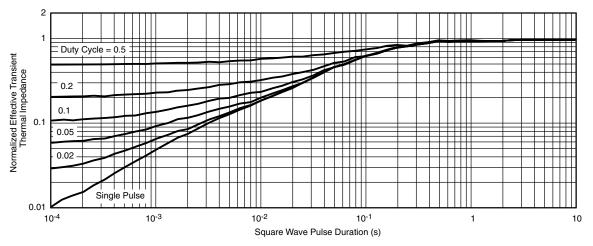
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

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## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg265049">www.vishay.com/ppg265049</a>.



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